Title: EASY MOUNT SOCKET
Assignee: Intel Corporation

In the Claims

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Please amend the claims as follows:

- 1-30. (Canceled)
- 31. (Currently amended) The mounting socket of claim[[ 30]] 39 where the spring is a coil.
- 32. (Previously Presented) The mounting socket of claim 31 where the conductive polymer is deformable when the spring is compressed.
- 33. (Currently amended) The mounting socket of claim[[ 30]] 39 where the vias have a constant width.
- 34. (Currently amended) The mounting socket of claim[[ 30]] where the conductive polymer fills the vias from side to side.
- 35. (Previously Presented) The mounting socket of claim 34 where the conductive polymer fills the vias from end to end.
- 36. (Currently amended) The mounting socket of claim[[ 30]] 39 where the terminals extend beyond the first and second sides of the body.
- 37. (Currently amended) The mounting socket of claim[[ 30]] 39 where the terminals are solderless.
- 38. (Canceled)
- 39. (Currently amended)—The mounting socket of claim-38 further comprising: A mounting socket, comprising:

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a body having first and second sides, and having a plurality of vias extending from a first side to a second side;

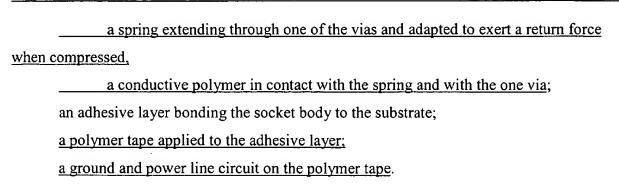
a plurality of conductive terminals within the vias, each terminal including

<u>a spring extending through one of the vias and adapted to exert a return force</u> when compressed,

- a conductive polymer in contact with the spring and with the one via;
- a first adhesive layer affixed to the first side of the body;
- a polymer tape applied to the first adhesive layer;
- a ground and power line circuit on the polymer tape.
- 40. (Previously Presented) The mounting socket of claim 39 further comprising a second adhesive layer applied over the ground and power line circuit.
- 41. (Currently amended) The mounting socket of claim[[ 30]] 39 further comprising a further adhesive layer affixed to the second side of the body.
- 42. (Canceled).
- 43. (Currently amended) The circuit assembly of claim[[ 42]] 44 where the conductive terminals exert a force upon the lands.
- 44. (Currently amended) The circuit assembly of claim 42 further comprising A circuit assembly, comprising:
  - a substrate having a plurality of lands thereon;
- a socket body having a first side in contact with the substrate, and having an opposite side;
  - a plurality of vias extending from the first side to the opposite side;
- a plurality of conductive terminals within the vias and contacting the lands, each terminal including

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- 45. (Currently amended) The circuit assembly of claim[[ 42]] 44 further comprising an integrated circuit coupled to the substrate.
- 46. (Previously Presented) The circuit assembly of claim 45 further comprising a circuit board contacting the opposite side of the socket body.
- 47. (Previously Presented) The circuit assembly of claim 46 further comprising another adhesive layer on the opposite side of the socket body bonding it to the circuit board.

48-56. (Canceled)